



SMD2016 HF Series Surface Mount PTC Devices

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Description

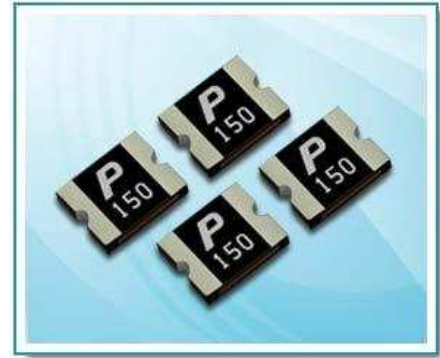
The 2016 series provides surface mount resettable overcurrent protection with holding current from 0.3A to 2.0A. This series is suitable for applications with higher holding current and higher working voltage up to 60V.

Features





- RoHS compliant and lead-free
- Halogen-free
- High voltage
- Low profile
- Fast response to fault current
- Compatible with high temperature solders

Applications



- Power over Ethernet (POE)
- Powered USB for POS and IPC
- Automotive electronics control module protection
- IEEE 1394 port protection
- Low voltage telecom equipment
- Industrial control
- Security systems



Agency Approval and Environmental Compliance

Agency	File Number	Regulation	Standard
	E201431		2002/95/EC
	R50099121		IEC 61249-2-21:2003

Electrical Characteristics

Part Number	I _{hold} (A)	I _{trip} (A)	V _{max} (Vdc)	I _{max} (A)	P _{d typ} (W)	Maximum Time To Trip		Resistance		Agency Approval	
						Current (A)	Time (Sec.)	R _{min} (Ω)	R _{1max} (Ω)		
SMD2016P030TF	0.30	0.60	60	20	1.40	1.50	3.00	0.500	2.300	✓	✓
SMD2016P050TF	0.55	1.10	60	20	1.40	2.50	5.00	0.200	1.000	✓	✓
SMD2016P100TF	1.10	2.20	15	40	1.40	8.00	0.50	0.100	0.400	✓	✓
SMD2016P100TF/33	1.10	2.20	33	40	1.40	8.00	0.50	0.100	0.400	✓	✓
SMD2016P150TF	1.50	3.00	15	40	1.40	8.00	1.00	0.070	0.180	✓	✓
SMD2016P200TF	2.00	4.20	6	40	1.49	8.00	3.00	0.048	0.100	✓	✓

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Note on Electrical Characteristics

■ Vocabulary

I_{hold} = Hold current: maximum current device will pass without tripping in 23°C still air.

I_{trip} = Trip current: minimum current at which the device will trip in 23 °C still air.

V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})

$P_{d\ typ}$ = Typical power dissipated from device when in the tripped state at 23 °C still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

R_{1max} = Maximum resistance of device at 23 °C measured one hour after tripping or reflow soldering of 260 °C for 20 sec.

- Value specified is determined by using the PWB with 0.090"*1.5oz copper traces.
- Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.
- Specifications are subject to change without notice.

Polymeric PTC Selecting Guide

■ Determine the following operating parameters for the circuits:

- Normal operating current (I_{hold})
- Maximum circuit voltage (V_{max})
- Maximum interrupt current (I_{max})
- Normal operating temperature surrounding device (min°C/max°C)

■ Select the device form factor and dimension suitable for the application:

- Surface Mount Device (SMD)
- Radial Leaded Device (RLD)
- Axial Leaded Device (ALD)
- DISC Device
- Other Customized Form Factors

■ Compare the maximum rating for V_{max} and I_{max} of the PPTC device with the circuit in application and make sure the circuit's requirement does not exceed the device rating.

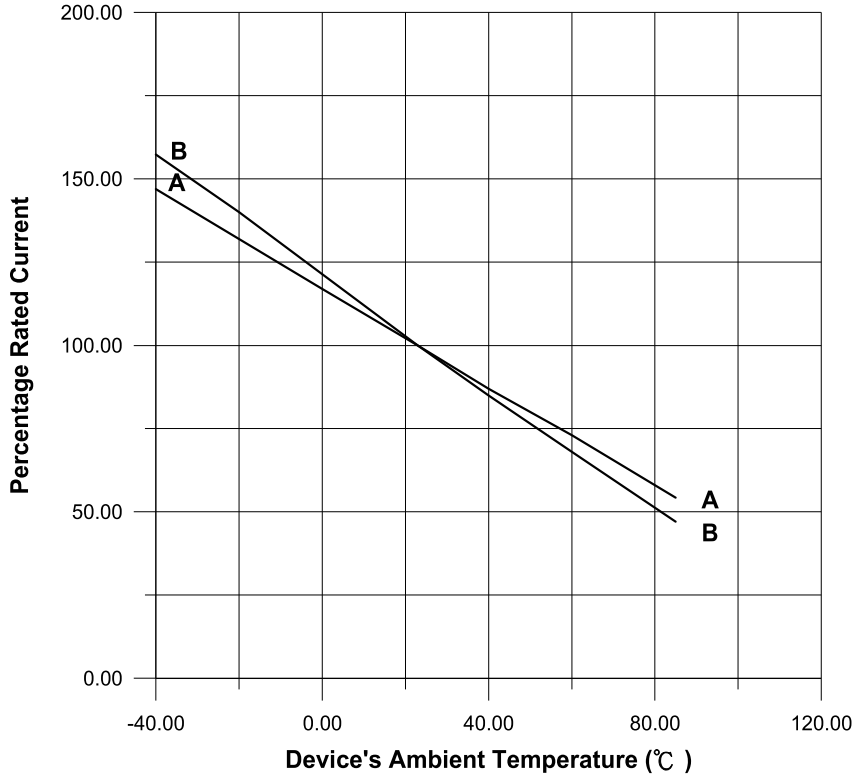
■ Check that PPTC device's trip time (time-to-trip) will protect the circuit.

■ Verify that the circuit operating temperature is within the PPTC device's normal operating temperature range.

■ Verify the performance and suitability of the chosen PPTC device in the application.

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Thermal Derating Curve



A—SMD2016P050TF
SMD2016P100TF
SMD2016P200TF
B—SMD2016P030TF
SMD2016P100TF/33
SMD2016P150TF

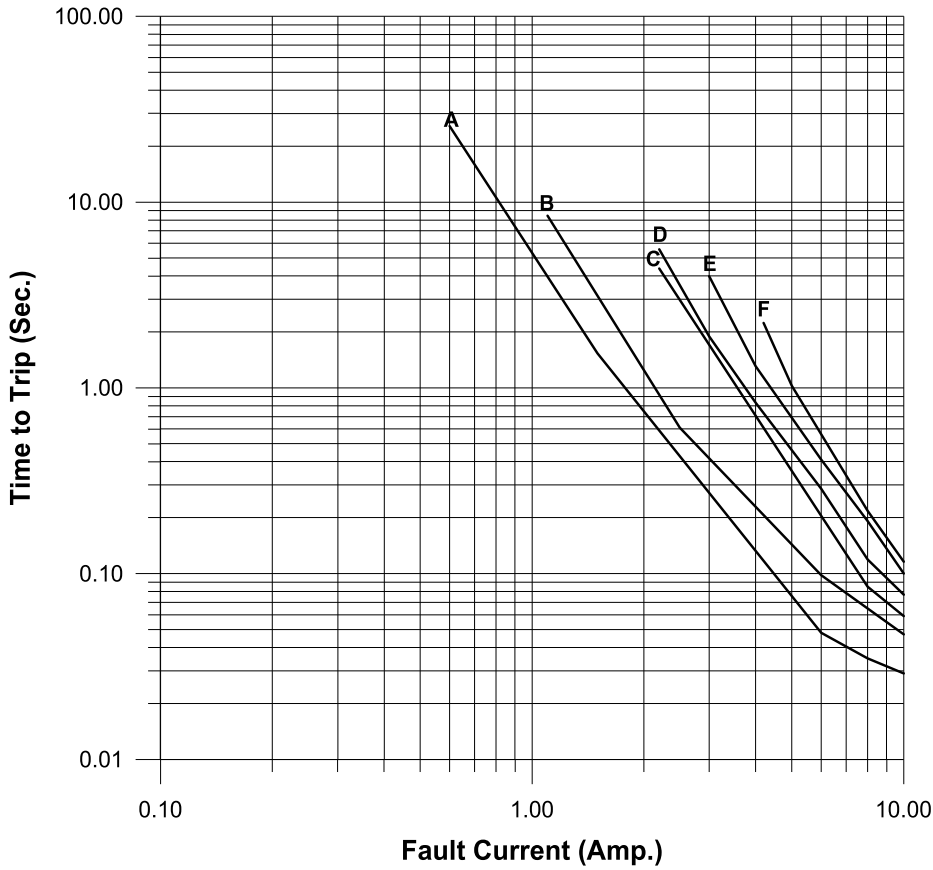
Thermal Derating Chart

Recommended Hold Current (A) at Ambient Temperature (°C)

Part Number	Ambient Operation Temperature								
	-40 °C	-20 °C	0 °C	23 °C	40 °C	50 °C	60 °C	70 °C	85 °C
SMD2016P030TF	0.45	0.40	0.35	0.30	0.25	0.23	0.20	0.18	0.14
SMD2016P050TF	0.93	0.80	0.65	0.50	0.42	0.38	0.33	0.30	0.23
SMD2016P100TF	1.66	1.47	1.29	1.10	0.91	0.83	0.73	0.64	0.50
SMD2016P100TF/33	1.66	1.47	1.29	1.10	0.91	0.83	0.73	0.64	0.50
SMD2016P150TF	2.26	2.00	1.76	1.50	1.24	1.13	1.00	0.87	0.68
SMD2016P200TF	2.80	2.50	2.19	2.00	1.84	1.74	1.50	1.34	1.14

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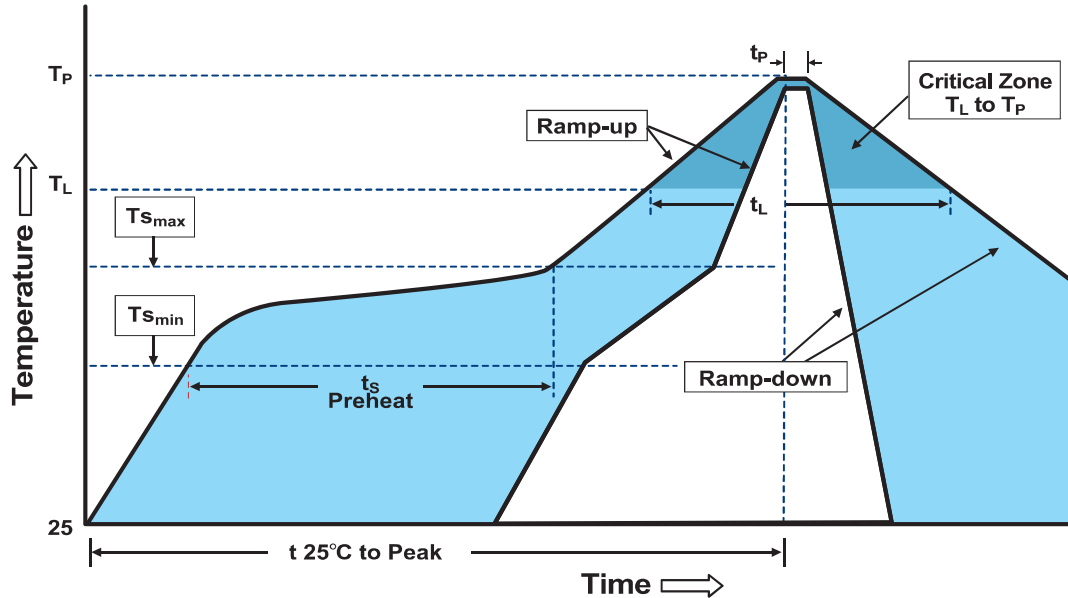
Average Time-Current Curve



- A—SMD2016P030TF
- B—SMD2016P050TF
- C—SMD2016P100TF
- D—SMD2016P100TF/33
- E—SMD2016P150TF
- F—SMD2016P200TF

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Soldering Parameters



Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate ($T_{s_{max}}$ to T_P)	3°C/second max.
Preheat	
-Temperature Min ($T_{s_{min}}$)	150°C
-Temperature Max ($T_{s_{max}}$)	200°C
-Time ($T_{s_{min}}$ to $T_{s_{max}}$)	60-180 seconds
Time maintained above:	
-Temperature (T_L)	217°C
-Time (t_L)	60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20-40 seconds
Ramp-Down Rate	6 °C /second max.
Time 25°C to Peak Temperature	8 minutes max.
Storage Condition	0°C ~35°C, ≤ 70%RH

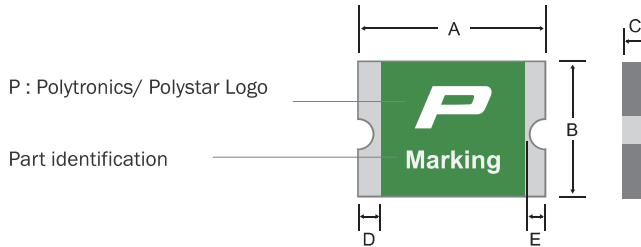
- Recommended reflow methods: IR, vapor phase oven, hot air oven, N₂ environment for lead-free
- Recommended maximum paste thickness is 0.25mm (0.010 inch)
- Devices can be cleaned using standard industry methods and solvents.

Note 1: All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

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Physical Dimensions (mm.)



Part Number	A		B		C		D		E	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
SMD2016P030TF	4.72	5.44	3.70	4.43	0.75	1.25	0.30	1.50	0.25	0.65
SMD2016P050TF	4.72	5.44	3.70	4.43	1.20	2.00	0.30	1.50	0.25	0.65
SMD2016P100TF	4.72	5.44	3.70	4.43	0.50	0.75	0.30	1.50	0.25	0.65
SMD2016P100TF/33	4.72	5.44	3.70	4.43	0.75	1.25	0.30	1.50	0.25	0.65
SMD2016P150TF	4.72	5.44	3.70	4.43	0.75	1.55	0.30	1.50	0.25	0.65
SMD2016P200TF	4.72	5.44	3.70	4.43	0.50	0.75	0.30	1.50	0.25	0.65

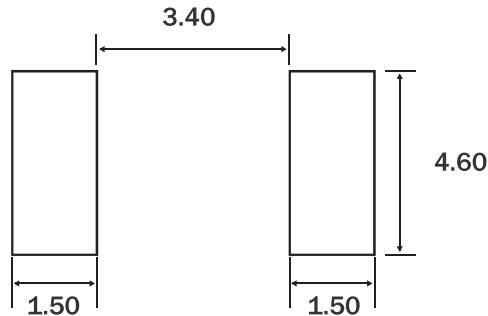
Environmental Specifications

Operating/Storage Temperature	-40°C to +85 °C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85°C , 1000 hours ±5% typical resistance change
Humidity Aging	+85°C , 85%R.H. 1000 hours ±5% typical resistance change
Thermal Shock	MIL-STD-202 Method 107G +85°C /-40°C 20 times -30% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215 No change
Vibration	MIL-STD-883C, Method 2007.1, Condition A No change
Moisture Level Sensitivity	Level 1, J-STD-020C

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Packaging Quantity and Marking

Recommended Pad Layout (mm.)



Part Number	Marking	Quantity
SMD2016P030TF	030	1500
SMD2016P050TF	050	1000
SMD2016P100TF	100	2000
SMD2016P100TF/33	1033	1500
SMD2016P150TF	150	1500
SMD2016P200TF	200	2000

© 12 mm tape on 7 inch reel per EIA-481-1 (equivalent to IEC286, part 3)

Physical Specifications

Terminal Material	Solder-Plated Copper (Solder Material: Matte Tin (Sn))
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/J-STD-002 Category 3.

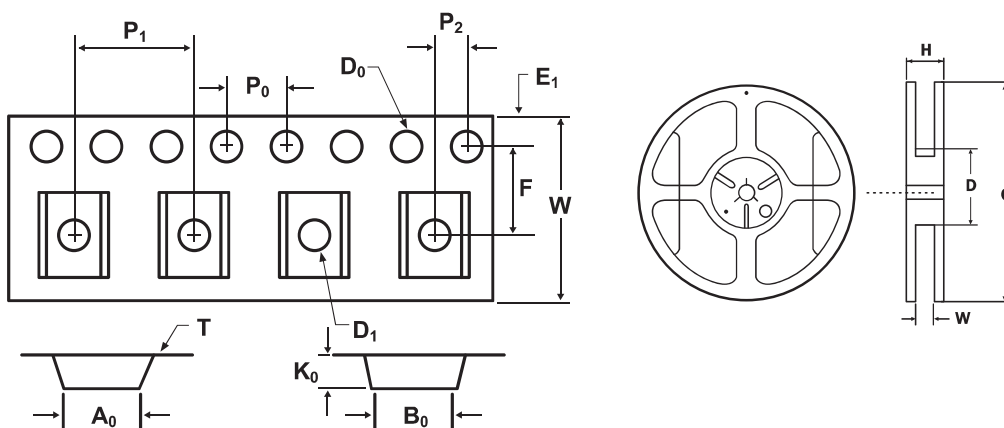
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Tape Specifications: EIA-481-1 (mm.)

	P100TF P200TF	P030TF P100TF/33 P150TF	P050TF
W	12.0 ± 0.30	12.0 ± 0.30	12.0 ± 0.30
F	5.50 ± 0.05	5.50 ± 0.05	5.50 ± 0.05
E ₁	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10
D ₀	1.55 ± 0.05	1.55 ± 0.05	1.55 ± 0.05
D ₁	1.50 (MIN)	1.50 ± 0.10	1.50 ± 0.10
P ₀	4.0 ± 0.10	4.0 ± 0.10	4.0 ± 0.10
P ₁	8.0 ± 0.10	8.0 ± 0.10	8.0 ± 0.10
P ₂	2.0 ± 0.05	2.0 ± 0.05	2.0 ± 0.05
A ₀	4.40 ± 0.10	4.48 ± 0.10	4.45 ± 0.10
B ₀	5.50 ± 0.10	5.40 ± 0.10	5.48 ± 0.10
T	0.25 ± 0.10	0.25 ± 0.10	0.25 ± 0.10
K ₀	0.75 ± 0.10	1.28 ± 0.10	1.86 ± 0.10
Leader min.	390	390	390
Trailer min.	160	160	160

Reel Dimensions: EIA-481-1 (mm.)

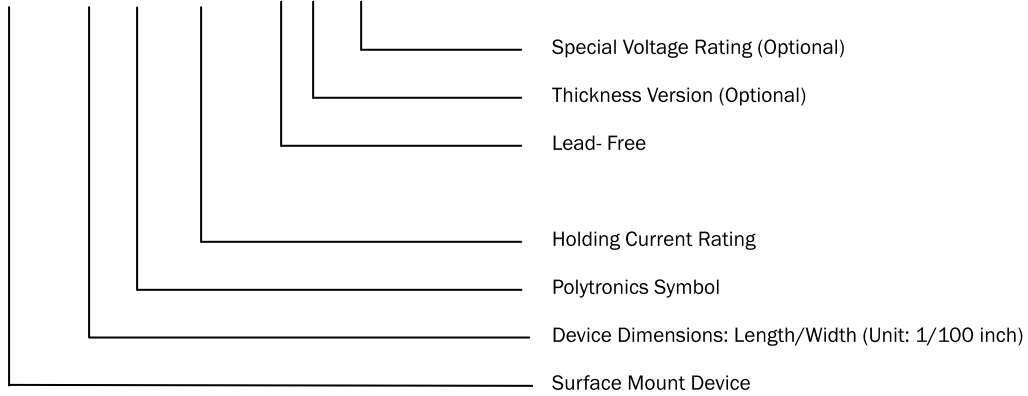
C	Ø178.0+/-1.0
D	Ø60.2+/-0.5
H	16.0+/-0.5
W	13.2+/-1.5



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Part Number System

SMD 2016 P □□□ **TF T** / □□



Cross Reference

Polytronics / EVERFUSE [®]	Cross Reference	
	Tyco / PolySwitch [®]	Bourns / Multifuse [®]
SMD2016P030TF	SMD030F-2018	-
SMD2016P050TF	decaSMDC050F/60	MF-SMDF050
SMD2016P100TF	SMD100F-2018	-
SMD2016P100TF/33	-	-
SMD2016P150TF	SMD150F-2018	MF-SMDF150
SMD2016P200TF	SMD200F-2018	MF-SMDF200

“EVERFUSE” is a registered trademark of Polytronics Technology Corp.

“Multifuse” is a registered trademark of Bourns , Inc.

“PolySwitch” is a registered trademark of Tyco Electronics.